

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2021 [Approved on 04 December 2025, 11:15 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.54%	Silicon	7440-21-3	100%
Die attach	Others (Rubber/non-thermoplastic Elastomer)	0.59%	4,4'-Sulfonylbisbenzamine	80-08-0	1%
			1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	7%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			Silver	7440-22-4	77%
Encapsulation	EP (Epoxy resin)	46.23%	3-(Trimethoxysilyl)propanethiol	4420-74-0	1%
			Carbon black	1333-86-4	1%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	1.5%
			Phenol, polymer with formaldehyde	9003-35-4	10%
			Fused Silica	60676-86-0	86.5%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.38%	PALLADIUM, ELEMENTAL	7440-05-3	3%
			COPPER, ELEMENTAL	7440-50-8	97%
Leadfinish	Tin plating	0.21%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	51.05%	Elemental iron	7439-89-6	2.6%
			COPPER, ELEMENTAL	7440-50-8	97.4%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-89 (JA) Pb & H-free_01	Diode / Transistor SMD	0.05598	g
